

Intelligent Half-Bridge Drivers

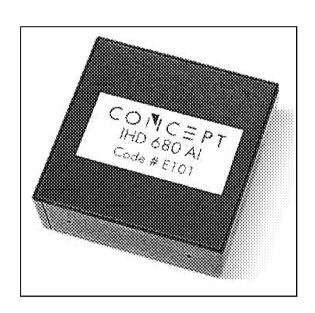
for IG BTs and PowerM O SFETs

Description

The intelligent half-bridge drivers of the IHD type series have been developed specifically for the reliable driving and secure protection of IGBT or power-MOSFET pairs.

All intelligent drivers of the HD type series have mutually compatible contacts and differ only in their drive performance.

There is no bgical link or mutual blocking between the control inputs of the two channels. This makes the drive components fully universals that they can be used for half-bridge, asymmetrical half-bridge and midpoint tapping circuits as well as for all other PW M converters and resonance topologies.



Product Highlights

- ✓ Suitable for G BTs and powerM O SFETs
- ✓ Protect the power transistors
- ✓ Extremely reliable, bng service life
- ✓ High gate current of ±1.5A to ±8A
- ✓ Electricalisolation 4000 Vac
- ✓ Electrically isolated status acknowledgment
- ✓ Monitoring of power supply and self-monitoring
- ✓ Switching frequency DC to MHz
- ✓ Duty cycle: 0...100%
- ✓ High dv/dtimmunity, guaranteed >50,000V/ μ s
- ✓ Shorten developmenttime

Applications

- ✓ Inverters
- ✓ M otordrive technology
- ✓ Traction
- ✓ Railroad power supplies
- ✓ Converters
- ✓ Powerengineering
- ✓ Sw itchm ode power supplies
- ✓ Radiobgy and bærtechnobgy
- ✓ DC/DC converter
- Research
- RF generators and converters



Absolute Maximum Ratings

Parameter Test conditions		min max		Unit
Supply voltage V_{cc}	Pin 10 to Pin 9	-0, 5	16	Vdc
G ate peak current I_{out}	IHD 215xx Pin 25 and 36	-1, 5	+1,5	A
	IHD 280xx Pin 25 and 36	-8	+8	A
	IHD 680xx Pin 25 and 36	-8	+8	A
Testvoltage (50Hz/1min)	IN xx to SO xx		50	Vac
	IN xx to GND und Vcc (see note 17)	4	4000	Vac
	N xx to output stages (see note 17)	4	1000	Vac
	GND/Vcc to output stages	4	1000	Vac
O perating temperature	HD xxxA N	0	+70	°C
	HDxxxA I	-4 0	+85	°C
Storage temperature	alltypes		+90	°C

Pin Designation

Pin	Desig.	Function	Pin	Desig.	Function
1	SO 1+	Status output + (CH.1)	36	G 1	Gate driver output (CH.1)
2	SO 1-	Status output - (CH .1)	35	COM1	Virtualcommon (CH.1)
3	IN 1-	Input inverting (CH.1)	34	Cs1	Bbcking capacitor (CH.1)
4	IN 1+	Inputnon-inverting (CH.1)	33	E1	Emitter/Source (CH.1)
5		free	32	REF1	External reference (CH.1)
6		free	31	Cb1	Blocking time capacitor (CH.1)
7		free	30	ME1	V ce m easurem ent (CH .1)
8		free	29		free
9	GND	Powersupply GND	28		free
10	Vcc	Power supply plusterm inal	27		free
11		free	26		free
12		free	25	G 2	Gate driver output (CH.2)
13		free	24	COM2	Virtualcommon (CH.2)
14		free	23	Cs2	Blocking capacitor (CH.2)
15	SO 2+	Status output + (CH.2)	22	E2	Emitter/Source (CH2)
16	SO 2-	Status output - CH.2)	21	REF2	External reference (CH.2)
17	IN 2-	Input inverting (CH.2)	20	Cb2	Blocking time capacitor (CH.2)
18	IN 2+	Inputnon-inverting (CH.2)	19	M E2	Væmeasurement (CH.2)

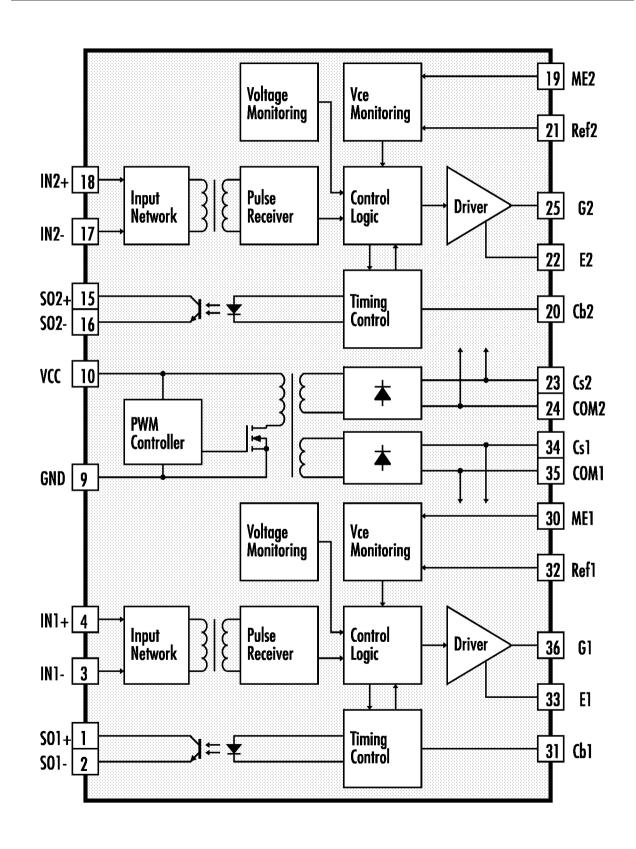
Legend:

(CH.1) = Channel1; (CH.2) = Channel2

Pinswith the designation "free" are notphysically present

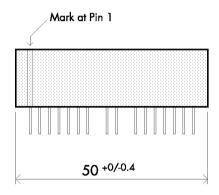


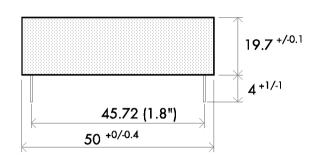
Block and Connection Diagram

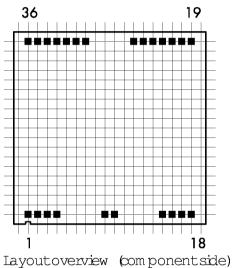




Mechanical Dimensions







Grid 2.54 Solderpads Ø 1.6 Drillholes Ø 0.9

Alldimensions are in mm

Case & Coating

Component	Material
Case product	N oryl (PPE m od.), non-halogenate flame retardants
Coating mass	Polyurethane base, tem perature-cycle resistant

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General Characteristics

Quality	Standard			
M anufacturing	ISO 9001 certified			
Reliability	Standard	t	ур	units
M TBF IHD215/280xx M TBF IHD680xx	M LHDBK 217F (eee Note 12) M LHDBK 217F (eee Note 12)		2,000,000 .,840,000	hours hours
Thermal Characteristics	Test Conditions	min	max	units
O perating temperature	HDxxxAN (see Note 13) HDxxxAI (see Note 13)	0 -40	+70 +85	°C
Storage temperature	alltypes	-4 0	+85	°C

Electrical Characteristics

Power Supply	Supply Test Conditions		typ	max	units
Supply voltage V_{cc} (see Note 1)	Pin 10 to Pin 9	12	15	16	Vdc
Supply current I_{cc} (see Note 2)	w ithout bad		90		m A
Max. supply current I_{cc}	IHD 215xx (see Note 3)			200	m A
Max. supply current I_{cc}	$\mathbb{H}D280xx$ (see Note 3)			200	m A
Max. supply current I_{cc}	IHD 680xx (see Note 3)			500	m A
Efficiency η	internalDC/DC converter		75		용
Tum-on threshold $V_{\it th}$	alltypes		10		Vdc
Hysteresis on-/off (see Note 4)	alltypes		0.6		Vdc
Inputs INx+ zu INx-	Test Conditions	min	typ	max	units
Input voltage V_{in} (see Note 5)	alltypes	14	15	16	Vdc
hputcument I in (see Note 6)	alltypes		180		mA (peak)
Input capacitance C_{in}	alltypes		470		pF
Coupling capacitance C_{io}	alltypes		10		рF
Rise time $t_{r(in)}$ (see Note 7)	alltypes	0		50	ns
Fall time $t_{f(in)}$ (see Note 7)	alltypes	0		50	ns
Vce-Monitoring	Test Conditions	min	typ	max	units
Inputs M E1 {and M E2}	to E1/COM1 {E2/COM2}	-0 .5		V_{cc}	Vdc



Electrical Characteristics (Continuation)

Timing Characteristics	Test Conditions	min typ max	units
Delay time input to output	tum-on $t_{pd(on)}$	60	ns
	tum-off $t_{pd(off)}$	60	ns
Delay time status output	atfailure (eee Note 16)	20	μs
Outputs G1 and G2	Test Conditions	min typ max	units
			_

Outputs G1 and G2	Test Conditions	min	typı	max	units
O utput current I_{out} (see Note 8)	⊮D 215xx	-1, 5		+1,5	Adc
	HD 280xx	-8		+8	Adc
	HD 680xx	-8		+8	Adc
O utput rise time $t_{r(out)}$ (see Note 9)	alltypes		15	30	ns
Output fall time $t_{f(out)}$ (see Note 9)	alltypes		15	30	ns
Totaloutputpower	HD 215xx		2		W
DC/DC-Converter)	HD 280xx		2		M
	HD 680xx		6		M
0 utputs S0 1/S0 2 (see Note 14)	alltypes		1		m A

Electrical Isolation	Test Conditions	min typ max	units
O perating voltage ($\sec N$ ote 10)	continuous or repeated (50Hz/1min) (see Note 17) EC 270 (see Note 15) all types (see Note 11)	600 1000	Vdc
Test voltage		4000	Vaceff
Partial discharge extinction volt.		1100	Veff
$max.\Delta V/\Delta tat\Delta V = 1000V$		50 100	kV/µs

Alldata refer to +25 °C and V_{cc} = 15V unless otherwise specified

Footnotes to the key data

- 1) At a supply voltage greater than 16V, the open-circuit voltages on the two output sides of the DC/DC converter may exceed 18V. This can lead to the destruction of the driver and protection circuits on the output side.
- 2) Only internal consumption of the drivers, static.
- 3) Exceeding of the current drawn indicates overload of the DC/DC converter. The next higher-rated type should be used.
- 4) The tum-off threshold is lower than the tum-on threshold by the magnitude of the hysteresis. The tum-on and tum-off thresholds allow the drivers to be run at operating voltages of 12V to 15V and cannot be changed.
- The drive signal should have the same amplitude as the power supply of the HDxxx. At V cc = 15V the drive signal should also be 15V, at V cc = 12V a drive signal of 12V suffices. Deviations of $\pm 1V$ are permissible.
- 6) Peak value during less than 100ns, after which a current of approximately 10mA flows and decays slow by thereafter.
- 7) If the rising or falling times are too high (i.e. driving is too slow), reliable transfer of the drive information cannot be guaranteed.



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- 8) The gate current must be limited to its maximum value by a gate resistor.
- 9) At a load of 10 nF in series with 20Ω .
- 10) Maximum continuous or repeatedly-applied DC voltage or peak value of the repeatedly-applied AC voltage between the inputs and outputs as well as between the power supply inputs and all other term in nals and between output 1 and output 2. Caution: in the case of a continuously-applied DC voltage of over 600Vdc between the signalization outputs and the outputs G1, E1 or G2, E2, the long-term characteristics of the optocouplers used for the state acknowledgment may become impaired. However, types rated and selected for higher partial discharge voltages are also available (see note 15).
- 11) This specification guarantees that the drive information will be transferred reliable even at a high dc-link voltage and fastests witching operations.
- 12) The M TBF (mean time between failures) is calculated to M ILHDBK 217F at an ambient temperature of $40\,^{\circ}C$, a typical bad and when the driver is exposed to a current of air. Further information on reliability may be obtained from CONCEPT upon request.
- 13) The application-specific self-heating of the drivers specially at high bad -must be taken into account.
- 14) The outputs SO 1/SO 2 are designed for an operating current of 1mA. A 50-year service life of the opto-couplers used is predicted at 1mA and an ambient temperature of 40 °C.
- 15) The partial discharge is not measured for the standard types. For main power applications, a sufficient safety margin exists between the typical operating voltage of < 600Vdc and the partial discharge extinction voltage of typically about 1500 Vpeak. Tested and selected types with guaranteed partial discharge immunity can be supplied for applications with maximum requirements and higher operating voltages (such as railroad applications).
- 16) In the case of a fault, the driver turns the power sem iconductor off almost without a delay. The acknowledgment runs through an optocoupler that has a delay time of about $20\mu s$. This means that the power transistor has a lieady been turned-off for about $20\mu s$ when the fault message reaches the control side.
- 17) The test voltage of 4000 Vac (m s)/50Hz may be applied only once during a minute. It should be noted that with this (strictly speaking obsolete) test method, some (minor) damage occurs to the isolation layers due to the partial discharge. Consequently, this test is not performed at CONCEPT as a series test. In the case of repeated isolation tests (e.g. module test, equipment test, system test) the subsequent tests should be performed with a lower test voltage: the test voltage is reduced by 500V for each additional test. The more modern if more elaborate partial discharge measurement is better suited than such test methods as it is almost entirely non-destructive.

Functional Description

Overview

The intelligent half-bridge drivers of the HD series are universal driver modules designed for power MO SFETs and IGBTs in switching operation.

All HD types have mutually compatible contacts and differ only in their drive performance (maximum gate current and output power of the DC/DC converter).

The HD types with higher output powers are outstandingly well suited for large

modules or a number of parallel-connected transistors as well as for high-frequency applications.

The intelligent half-bridge drivers of the HD series represent a complete solution for all drive and protection problems in connection with power MO SFET and ISBT power stages. Practically no additional components are required in the control circuitor in the power section.



Reliable operation

Gate driving with a positive and negative control voltage (depending on the selected supply voltage between ± 12V and ± 15V) allows reliable operation of GBT modules of any size from any manufacturer. Thanks to the great interference immunity achieved by using a negative gate voltage, a number of power MOSFET or GBT modules can be connected in parallel without having to worry about parasitic switching operations or oscillations.

The components of the HD type series contain - for each of the two channels - an electrical isolation between the control and power sides, an overcurrent and short-circuit protection circuit for the power transistors, a supply-voltage monitoring circuit, a state acknowledgment circuit as well as an electrically-isolated supply of the drive electronics via an integrated DC/DC converter.

The two drive channels operate independently of each other, there is no mutual brical linking or blocking.

Genuine electrical isolation

The electrical isolation realized on the basis of the transformer principle at operating voltages of up to 1000V (corresponding to a test voltage of 4000V) between the control and power sections as well as the extremely high interference immunity of at least 50,000V per microsecond predestine the drive modules of the IHD series to applications in which large potential differences and large potential jumps occur between the power section and the controlle betronics.

Application benefits

The extraordinarily short delay times of the drivers of the HD series perm it their use in high-frequency switchmode power-supplies, high-frequency converters and resonance converters. Thanks to their extremely short delay times through the driver, they ensure trouble-free operation in bridge circuits, and their outstanding properties also preclude any offset problems.

The use of driver modules of the HD series means that power stages with power MO SFETs or GBTs can be realized within an extremely short time.

Short-circuit and overcurrent protection

One of the basic functions of the intelligent half-bridge drivers of the HD series is to ensure reliable protection of the controlled power transistors against overcurrent and short circuit. The current measurement is based on the determination of the drain source or collector-emitter voltage at the activated transistor. If a threshold defined by the user is exceeded, the power transistor is turned off and remains blocked in this state for a defined minimum time. After this time has elapsed, the transistor is turned on again synchronously with the next turn-on edge of the drive signal.

This protection concept can be used to protect IGBT half-bridges and three-phase modules in an effective and reliable way.



Layout of the terminals

The term inalpins of the drive modules of the HD series are arranged so that the layout can be kept very simple and the bgic signal flow (input signal \Rightarrow drive circuit \Rightarrow power transistors) is maintained. A distance of 45 mm is observed between the drive signal and the power potential!

Note on pin description

As the drivers of the HD series have two channels, all pins are present in duplicate with the exception of the power supply. In the description, the pin numbers and designations are given for channel 1. Those for channel 2 are shown in braces {}.

For the second channel, the same applies as for the first channel that is explicitly described.

Pin 3 and 4 {pin 17 and 18}: Inputs IN1+ and IN1- {IN2+ and IN2-}

The drive signals are applied to the difference inputs N1+ and N1-. The input N1-is usually connected to the ground of the controlelectronics. A positive edge at

input N1+ causes the corresponding power transistor to be turned on, a negative edge switches it off again (Fig. 1). If the drive signal has to be inverted, then input N1+ is applied to the electronics ground and the control signal to input N1- (Fig. 2).

In the drivers of the HD series, the electricalisolation of the control signals is realized by the use of pulse transformers. Care should be taken when applying the drive signal that the control electronics can supply the voltages charge/discharge currents required by the IHD and that the edge slope comesponds to the data-sheet specifications. In addition, the input driver must be protected against latch-up, as reactive effects from the switching operations are transferred to the input drivers via the coupling capacitance of the internal transformer. The MC33151 from Motorola is a tried and tested input driver for both channels.

The drive modules of the HD series should be positioned as closely as possible to the relevant power transistors. The leads from the control electronics to the inputs N 1+ and N 1- can be about 25 cm in length. The leads N 1+ and N 1- must run in parallel and be well coupled (parallel tracks or twisted pairs).

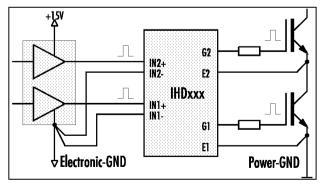


Fig. 1 Non-inverting input configuration

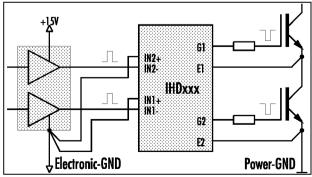


Fig. 2 Inverting input configuration



The minus leads must always be run back separately for both channels to the input driver so that reliable operation can be ensured (see Fig. 3).

W hereas reliable transmission is no problem in the case of very bng pulses, the entire configuration must be checked with a view to very short drive pulses: although many level shifters and most driver Is generate a fast and distortionfree tum-on edge at such shortpulses (less than 100 ns), the tum-off edge that folbws shortly afterwards may be distorted or sbwed down. In such a case, a driver may be turned on by a short pulse but may not turn of fagain due to the distorted tum-off edge. The input driver upstream of the IHD must thus be optimized to ensure that the tum-offedge is always just as fast and distortion-free -especially with short pulses - as the tum-on edge. In (digital) systems that intrinsically preclude the occurrence of drive pulses shorter than about 200 ns, this operating case need notbe specially checked.

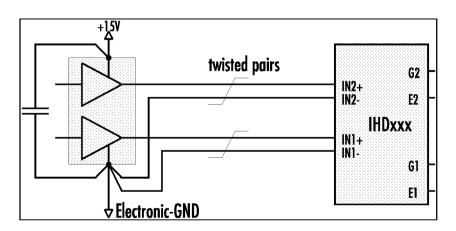


Fig. 3 Correct input driver wiring

Pin 1 and 2 {pin 15 and 16}: Outputs SO1+ and SO1- {SO2+ and SO2-}

The outputs SO 1+ and SO 1-are used for the status acknow ledgment. These are the collector (\$01+) and emitter (\$01-) of an opto-coupler transistor. The throughswitched state of this transistor corresponds to an "everything OK" message. If the voltage supply is too bw or the protective function is activated, the transistor opens (see Fig. 4). The outputs are designed for an operating current of 1 mA. Despite electrical isolation with respect to all other contact pins, these outputs can be used exclusively at the potentialofthe controlside # 50V difference to the drive signal), as there is only a minimum distance to the terminals of the inputs N 1+ and N 1-.

The capacitive coupling between transmitter and receiver in the optocouplermeans that under certain conditions short spikes may occur at the outputs SO 1/SO 2 due

to high level jumps of the power transistors. It is therefore recommended to connect an RC network with a time constant of about 5...10 microseconds after the status outputs.

It is further recommended not to hardwire two or more status acknowledgment outputs but to feed their individual signals to the monitoring electronics. This simplifies diag-

nosis and troubleshooting in the event of errors to a very decisive degree.



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Pin 9 and 10

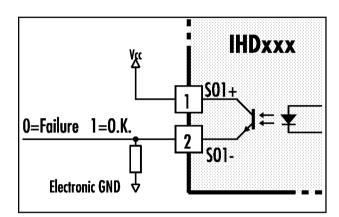


Fig. 4 Status acknow Ledgem entoutputs

GND and Vcc

These contacts are used for the power supply of the driver module. The nominal supply voltage is 12V to 15V. In order to ensure reliable starting of the integrated bw-inductance DC/DC converter, а electrolytic capacitor with high ripple current capability must be placed in the immediate proximity of pins 9 and 10. Its capacitance should not be smaller than the sum of the capacitances connected to terminals Cs1 (pin 34) and Cs2 (pin 23). The current drawn is determined by the number of transistors driven, their gate capacitance and the switching frequency.

Due to the high isolation of the supply term in als compared with all other pins, the drivers of the HD series can be supplied by any potential. It need not necessarily be identical with the input potential.

The internal tum-on thresholds were also designed to perm it operation at 12V. This makes sense above all when using transistors that have very large short-circuit

currents at higher gate voltages (bw saturation types).

It should be noted that the drivers them selves are not protected against selfoverbad. A short circuit between the gate
and emitter terminals - caused by a
defective power semiconductor, for
example - can lead to them aldestruction
of the driver.

Pin 36 {pin 25} Output G1{G2}

Output $G1\{G2\}$ is the driver output for the gate driving. This is effected with \pm 12V to \pm 15V depending on the supply voltage, or with only a positive gate voltage depending on the power transistors used and the application (see description of pin 35, COM1).

The output stages of the drivers of the HD series are very ruggedly dimensioned. The maximum permissible gate charge/discharge current has a value of 1.5A for the HD215 and 8A for both the HD280 and the HD680. This allows the largest G BT and power M O SFET modules to be driven. It is also possible to directly drive a number of power modules connected in parallel. The charge/discharge current must be limited by an external gate resistance. It should be noted that the total voltage rise (twice 12V to 15V) must be taken into account at ± driving of the gate.

The gate of the power transistor must be connected via a lead of shortest possible length with terminal G1 {G2}. To allow the switching speed to be set independently at both turn-on and turn-off, a design with two gate resistors and a diode can be used (see Fig. 5).



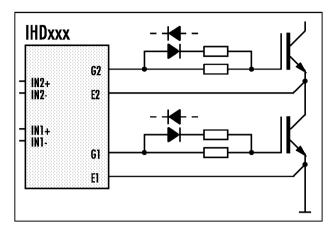


Fig. 5 A sym metrical gate resistors

It is mandatory to connect zener diodes (anti-series connected) directly between the gate and emitter for IGBTs. Their zener voltage must correspond exactly to the selected gate voltage (12V to 15V) (see Fig. 10). They prevent the gate voltage from rising due to parasitic effects (e.g. the Miller effect) to a value exceeding the nominal gate voltage. An excessive gate voltage increases the short-circuit current to an overproportional degree and can lead to destruction of the power sem iconductors.

A sufficiently low-resistance term ination of the gate is ensured by the driver module even when this is not supplied with the operating voltage.

Pin 33 {pin 22} Terminal E1 {E2}

This term inal must be connected to the emitter or source term inal of the power transistor. The connection to the emitter or source term inal of the power element must be as short and direct as possible. For modules with an auxiliary emitter or source this auxiliary term inal must be used. The term inal is also used as the bw

end of the reference, whereby the latter should be connected to the term inalE1 of the driver module as directly as possible.

If the connections between a driver of the HD series and a power transistor are implemented via link circuits, then a length of 10 cm should not be exceeded and the leads G1, E1 as well as the measurement terminal (collector or drain terminal) must be run in the form of twisted wires for each transistor (see Fig. 9).

Pin 30 {pin 19} Terminal M E1 {M E2}

This terminal is used for measuring the voltage drop at the activated power transistor (in an on-state condition) in order to ensure protection against short-circuit and overbad. It should be noted that this term inal may under no circum stances be connected directly to the drain or collector of the power transistor. In order to protect the measurement terminal from the high drain or collector voltage of the deactivated powerelement, a circuit with a high reverse-blocking-voltage diode (Dme) or series-connected diodes of type 1N 4007 should be provided (see Figs. 6 and 10). It is absolutely mandatory to overdimension these diodes with respect to voltage.

A pull-up resistor integrated in the module ensures that when the power transistor is activated, a current flows through the measurement diode (Dme), the damping resistor (Rme) and the transistor. Thus the potential present at measurement input ME1 corresponds to the forward voltage



of the activated transistor plus that of the diode and the voltage drop at Rme. Rme attenuates the reverse current peaks of the measurement diode Dme and should be set to 68Ω .

It should be noted that the power transistors do not turn on immediately - for IS BTs in particular, several microseconds may elapse before they have completely switched through. In conjunction with the integrated pull-up resistor and the external capacitor (Cme), this leads to a delay in the measurement after the power transistor is turned on. This delay shall henceforth be called the response time. The borger it takes the power transistors to turn on, the higher must the selected response time (and thus Cme) be. The formula for dimensioning Cme can be found on page 16.

It should also be borne in m ind that negative voltages are not permitted at the measurement input.

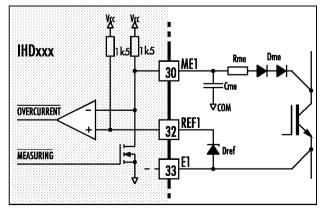


Fig. 6 Principle of the Voe monitoring

Pin 31 {pin 20} Terminal Cb1{Cb2}

After the current monitoring circuit has responded, the power transistor is turned offby the protection function of the intelligent driver and remains blocked in this state for a defined minimum time. This function is used to protect the component from them aloverbad under a continuous or recurring short-circuit. This blocking time can be defined by connecting pin 31 (Cb1) via a capacitor to pin 35 (COM 1) (orpin 20 (Cb2) to Pin 24 (COM 2)) (see page 16 for the relevant formula). The capacitance of the blocking capacitor should not exceed a value of 470nF.

During the blocking period, the response of the protective function to overcurrent is signaled at outputs SO 1+ and SO 1-{SO 2+ and SO 2-}.

A fler the blocking period has elapsed, the power transistor is not turned on again until the following turn-on edge arrives (see Fig. 7).

Pin 32 {pin 21} Terminal REF1 {REF2}

An external zener diode is connected to this pin as a reference. It defines the maximum voltage drop across the activated power transistor at which the protective function of the drive circuit is activated and thus the power transistor is turned off.

The protective functions of the intelligent half-bridge drivers of the HD series always become active when the voltage at ME1 {ME2} (measurement



drain/collector) is higher than that at REF1 {REF2} (see Figs. 6 & 7).

The reference potential is pin 33 (£1). The reference may not be blocked by capacitors under any circum stances.

The reference diode must be boated as cbse as possible to the driver module.

Pin 34 {pin 23} Terminal Cs1 {Cs2}

Iow-inductance blocking capacitors with high ripple current capability (electrolytic capacitors are usually used) are connected to these outputs. They decouple the DC/DC converter on the secondary side and must be able to supply the pulse

8A) currents (up to for charging/discharging the gate capacitances. They are connected between Cs1 $\{Cs2\}$ and $COM1 \{COM2\}$. As the charge/discharge currents for the gate capacitance are largely drawn from these electrolytic capacitors, these must be bcated in the immediate proximity of the driver module. The term inal assignment is optimally suited for this purpose. Capacitance values of up to 100 µF per channel are recommended. Greater values should not be used to ensure that the integrated DC/DC converter starts with no problems.

In order to avoid the operating voltage from "running-up" on the secondary side, a 16V-zener diode or a transient

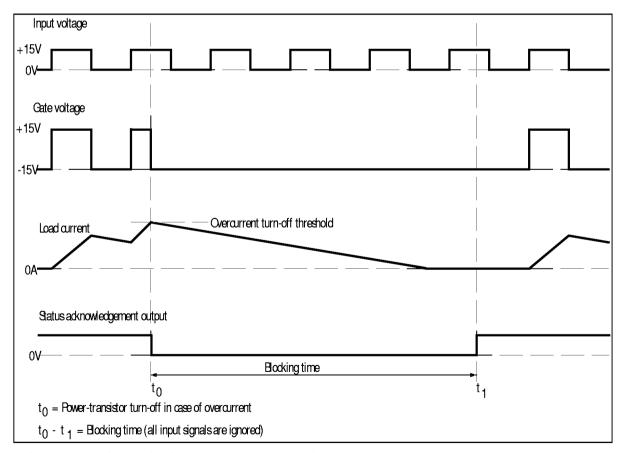


Fig. 7 Function principle of the blocking time



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suppressor must be connected in parallel to the blocking capacitors. These diodes are required on both channels, even if one channel is not used. They should be rated for a power dissipation of 1.3W.

Pin 35 {pin 24} Terminal COM1{COM2}

This is the ground term inal of the secondary-side blocking capacitor. It is simultaneously used as the reference potential for the measurement filter and the capacitors Cb1 {Cb2}.

In place of E1 {E2}, the term inal COM 1 {COM 2} can also be connected to the source of a power MO SFET. In this case, the reference must also applied to this term inal. This circuit allows power MO SFETs to be driven without a negative gate voltage. The transistor is then driven in its deactivated state with OV (unipolar gate driving, see Fig. 8).

The terminal E1 $\{E2\}$ is unused in this circuit and may under no circum stances

be connected with $COM1\{COM2\}$.

As a rule, this method of gate driving is not useful for GBTs, as it is necessary to work with a negative gate voltage, especially with Japanese chips and larger modules.

Configuration within the Power Section

The drivers of the HD series should be boated as closely as possible to the power transistors. The connecting leads to the transistors should be as short as possible, i.e. they can be up to 10 cm long depending on the gate current and switching speed. In contrast, the input leads may be about 25 cm in length (see Fig. 9). But as has already been described, care should be taken to ensure that all leads are run in a neat pattern.

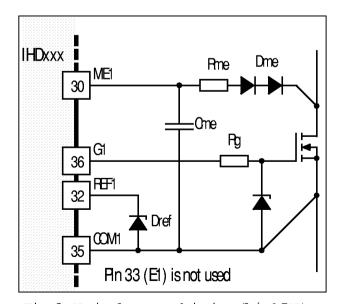


Fig. 8 Unipolar gate driveing (0/+15V)



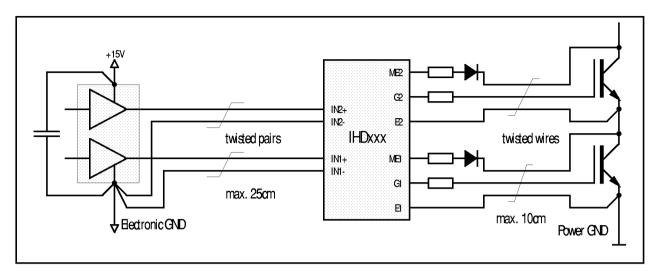


Fig. 9 Correct input and output wiring

Formulas for Circuit Calculations

Response Time Capacitor

$$C_{me} = ----\frac{t_a}{-}-----$$

$$1,5k\Omega \ln \left(-\frac{V_{CC}}{-}--\right)$$

Blocking Time Capacitor

at±15V gate driving

$$C_{b} = -\frac{t_{0}}{71,6k\Omega}$$

 $C_{b,max} = 470 nF$

atunipolargate driving (0/+15V)

$$C_b = ----\frac{t_0}{-}-----$$

$$100k\Omega \ln \left(\frac{2 \cdot V_{cc}}{V_{ref}}\right)$$

 $C_{bmax} = 470 nF$

Illustrative Application: 80 kW Converter

Fig. 10 shows one phase of a three-phase converter for a power of about 80 kW. The useful output power naturally depends on the dc-link voltage and the switching frequency of the converter. The HD680 albwed the converter to be operated with frequencies up to far above 20 kHz in principle, although at these frequencies considerable switching losses occur in the IGBTs and the output power must be correspondingly reduced. The driver power of the HD680 is also sufficient for a parallel circuit comprising several modules of this type. For switching frequencies below 10 kHz, one HD280 is sufficient for this GBT module.

The complete three-phase converter is available in the circuit displayed (Fig. 10) as a completely assembled and tested evaluation board from CONCEPT (see also the section on "Evaluation boards"). The evaluation board is also equipped with an electrolytic battery of very bw-inductance design.

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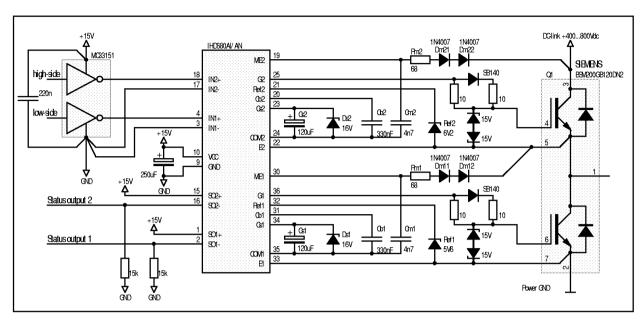


Fig. 10 Application with a HD 680A I/AN: One phase of a 80kW -Inverter

As indicated in the circuit diagram, the drive leads should be connected as closely as possible to the IS BTs. Special connectors are provided for the gate and emitter. Unfortunately, however, the module has no collector-sense term inals. The auxiliary emitter term inalof the "upper" IS BT is an obvious choice for the Voe measurement of the "lower" IS BT (see also Fig. 11). The Voe measurement output should under no circum stances be connected to power term inal 1 of the module, as this is very unfavorably positioned as regards its geometry and the di/dt change in the bad current falsifies the measurement. For

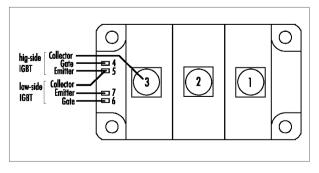


Fig. 11 Correct driver connection with an GBT half-bridge module

the Voe measurement of the "upper" Is BT there is no alternative to using power terminal3 (see also Fig. 11). But this has a more favorable geometry than terminal 1 and the result is acceptable. The voltage drop caused by the di/dt current change in the module—internal feeder lead from terminal 3 to the Is BT chip also explains why reference diode Ref2 shows a higher value than Refl so that the overcurrent protection for both Is BTs becomes active at about the same current values.

Evaluation Boards

To allow the user to enter quickly and smoothly into GBT technology and into the protection concept used for the intelligent half-bridge drivers of the HD series, CONCEPT offers various evaluation boards and power stages. Completely assembled and tested half-bridge evaluation boards are available with various types of GBT.



In addition, CONCEPT offers ready designed and assembled three-phase bridges with IGBT modules. Additional documentation on these is available upon request.

These boards can be used in conjunction with the documentation to build ready-to-use prototype equipment in a few hours.

Supplementary Services

CONCEPT makes the practical experience gained over many years by its development and application engineers available to all interested users. CONCEPT offers various services within the scope of this offer:

Consulting and Training

CONCEPT provides consulting and training services to customers on optimal procedures, the ideal circuit topology and the avoidance of possible difficulties in the development of power electronics.

Technical Support

CONCEPT offers you fast and effective help for your questions and problems:

E-M ail: concept@ bielstar.ch Tel++41 (0)32 / 322 42 36 Fax ++41 (0)32 / 322 22 51

Application

CONCEPT calculates and dimensions power sections and driver circuits according to the customer's specifications and supplies complete circuit diagrams, parts lists and electrical and them alkey data of the circuit. The customer then implements the layout and construction of the equipmenthim self.

Customer-Specific Systems

CONCEPT develops and produces complete equipment and systems according to the customer's specifications.

Quality

The obligation to high quality is one of the central features laid down in the mission statement of CT-Concept Technology Ltd. Total Quality Management (IQM) covers all stages of product development and production up to delivery. The drivers of \mathbb{H} D series are m anufactured the according the ISO 9001 to quality standard.

Exclusion Clause

CONCEPT reserves the right to make modifications to its technical data and product specifications at any time without prior notice. The general terms and conditions of delivery of CT-Concept Technology Itd. apply.



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Ordering information

Drivers for low power (2W cnverter, ±1,5A gate current)

Standard version $(0...70 \,^{\circ}\text{C})$ HD 215 AN hdustry version $(40...+85 \,^{\circ}\text{C})$ HD 215 AI

Drivers for medium power (2W converter, ±8A gate current)

Standard version $(0...70 \,^{\circ}\text{C})$ HD 280 AN Industry version $(40...+85 \,^{\circ}\text{C})$ HD 280 AI

Drivers for high power (6W converter, ±8A gate current)

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Drivers for high isolation voltages (i.e. railroad applications)

Please request further information

Evaluation boards

Please ask for an overview of our evaluation boards

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